

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

28.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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C-RS Panasonic R-F770-ED 18-50-00	50200950	18 50	VS	1	
A-RAS-FR4-PP-106-H72-TG170-LowFlow-EM...	50203100	45		2	A01
A-RS-FR4-ML-0.508mm-018+018-TG150-HF-...	50203031	18 508 18	L2 L3	3	A02
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	120		4	B00
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5	
A-RS-FR4-ML-0.508mm-018+018-TG150-HF-...	50203031	18 508 18	L4 L5	6	A03
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...	50202996	91		7	
C-RAS-FR4-PP-106-H71-TG150-HF-EM-37B(...	50202996	0		8	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	9	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point:

(05) over SM and galv. Cu; both sides

nominal:

1430 µm

Version 1.2.20.35

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